

# LNJ318C83RA

## High Bright Surface Mounting Chip LED

Dome-Lens Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	55	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

■ Lighting Color

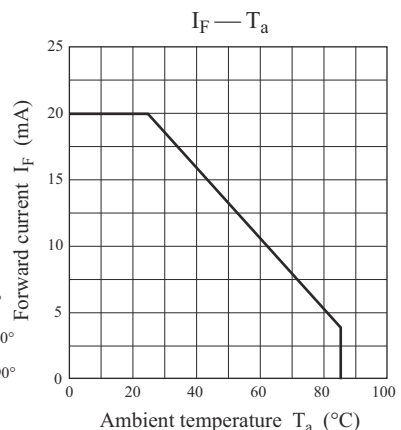
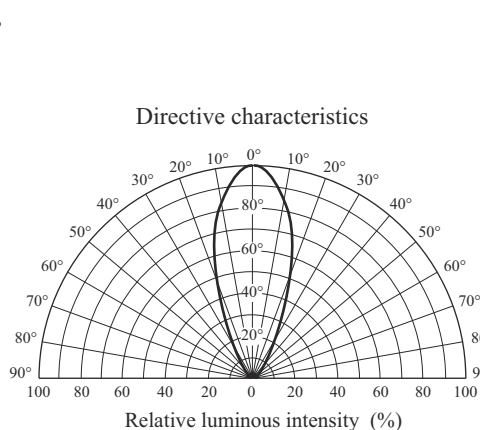
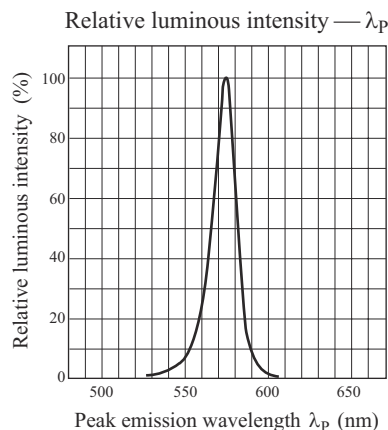
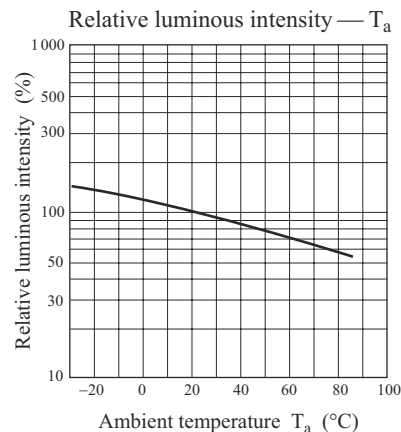
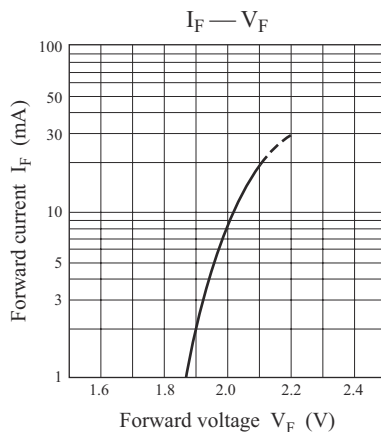
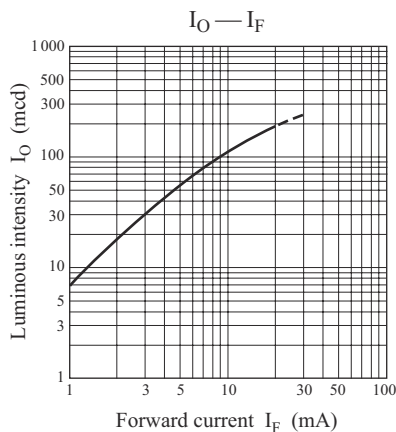
- Yellow Green

Note) \*: The condition of  $I_{FP}$  is duty 10%, pulse width 10 ms.

■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

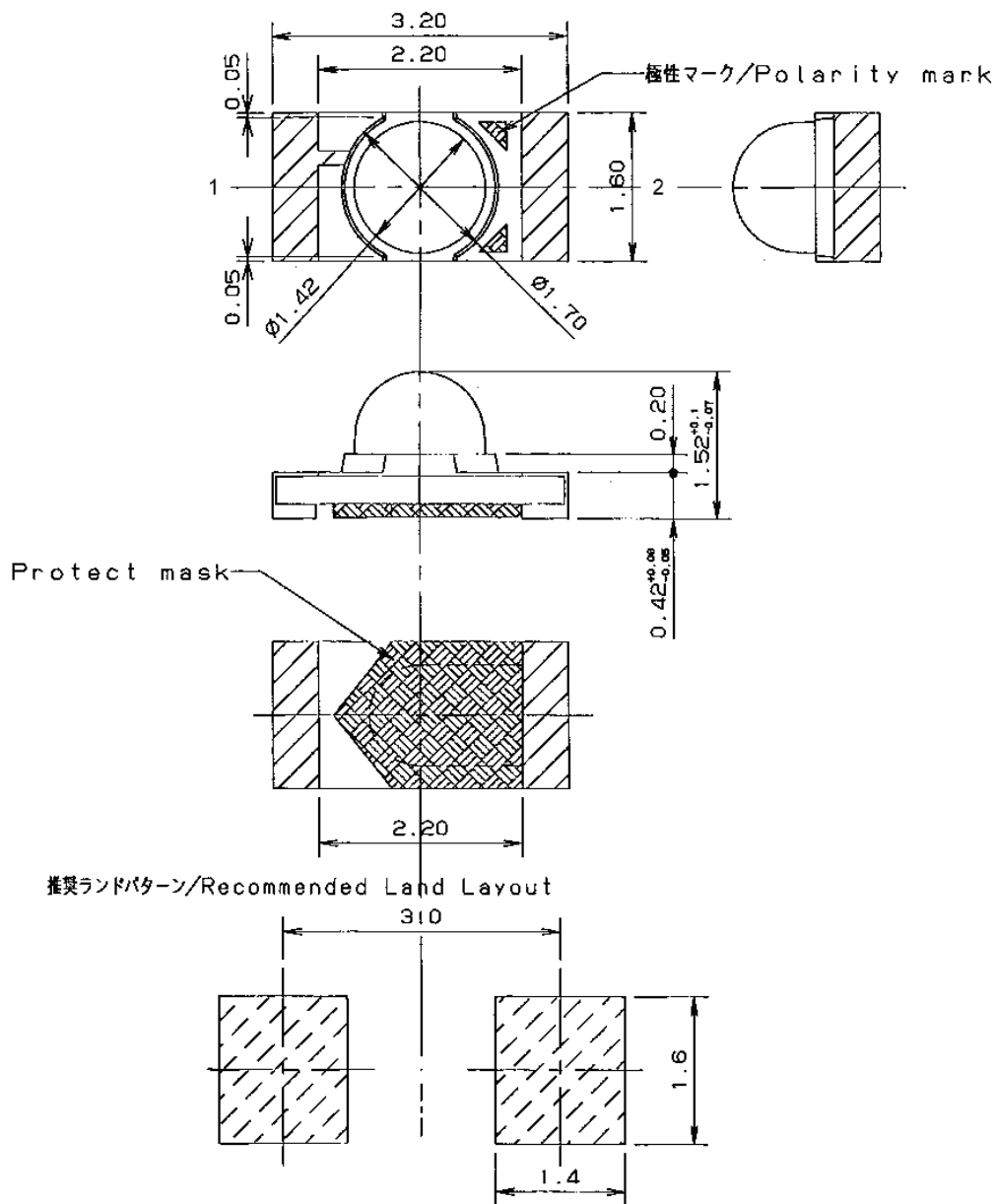
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$	$I_F = 10\text{ mA}$	58	110		mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.03	2.5	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		575		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm

Note) Be careful of the product destruction by static electricity.



■ Package (Unit: mm)

KLTLTN2K1800



- Pin name
- 1: Anode
- 2: Cathode

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